

## ABSTRACT OF THE DISCLOSURE

A method for manufacturing a semiconductor package is disclosed. A wafer including a plurality of semiconductor chips is provided. Each chip has one or more mirrors mounted thereon. Further, a plurality of bond pads formed on a periphery of the chip. Next, 5 a photoresist is formed over the one or more mirrors. Then, the semiconductor chips are singulated from the wafer. One ore more semiconductor chips are mounted on a base substrate. The bond pads of the semiconductor chip are electrically connected with the base substrate. The photoresist is then removed from the semiconductor chips.